

P-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^d	Q _g (Typ)			
- 60	0.053 at V _{GS} = - 10 V	- 25	26			
- 80	0.062 at V _{GS} = - 4.5 V	- 20	20			

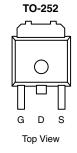
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC

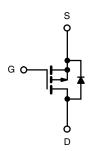


APPLICATIONS

- · High Side Switch for Full Bridge Converter
- DC/DC Converter for LCD Display



Drain Connected to Tab



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise note)						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V _{DS}	- 60	V			
Gate-Source Voltage	V _{GS}	± 20	V			
Continuous Drain Current (T _J = 150 °C)	T _C = 25 °C	I-	- 25	^		
Continuous Drain Current (1) = 130 °C)	T _C = 125 °C	l _D	- 20			
Pulsed Drain Current	I _{DM}	- 100	Α			
Avalanche Current, Single Pulse	L = 0.1 mH	I _{AS}	- 22			
Repetitive Avalanche Energy, Single Pulse ^a	L = 0.1 min	E _{AS}	24.2	mJ		
Device Discinction	T _C = 25 °C	Pn	38.5 ^c	W		
Power Dissipation	T _A = 25 °C	1 ^{FD}	2.3 ^{b, c}			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Marrian un lumation to Anchionab	t ≤ 10 s	R _{thJA}	17	21		
Maximum Junction-to-Ambient ^D	Steady State	' 'thJA	45	55	°C/W	
Maximum Junction-to-Case		R _{thJC}	2.7	3.25		

Notes:

- a. Duty cycle \leq 1 %.
- b. When mounted on 1" square PCB (FR-4 material).
- c. See SOA curve for voltage derating.
- d. Based up on T_C = 25 °C.



Parameter	Symbol	Test Conditions	Min .	Тур.	Max.	Unit	
Static				•	•		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 60			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = - 60 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			- 50	μΑ	
		$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 150 ^{\circ} \text{ C}$			- 125		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = -5 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α	
		V _{GS} = - 10 V, I _D = - 10 A	0.053		0.060		
Drain Course On State Desistance	Book	$V_{GS} = -10 \text{ V}, I_D = -10 \text{ A}, T_J = 125 ^{\circ}\text{C}$			0.102	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 10 A, T _J = 150 °C		0.120		_ \ \\ \\ \\ \\ \	
		V _{GS} = - 4.5 V, I _D = - 5 A		0.062	0.070	0	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 10 A		22		S	
Dynamic ^b							
Input Capacitance	C _{iss}			1140	1710	pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = -25 \text{ V}, f = 1 \text{ MHz}$		130			
Reverse Transfer Capacitance	C _{rss}			90			
Total Gate Charge ^c	Qg			26	40		
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -10 \text{ A}$		4.5		nC	
Gate-Drain Charge ^c	Q _{gd}			7		•	
Gate Resistance	R _g	f = 1 MHz		7		Ω	
Turn-On Delay Time ^c	t _{d(on)}			8	15		
Rise Time ^c	t _r	V_{DD} = - 30 V, R_L = 3 Ω		9	15		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong -19 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 2.5 \Omega$		65	100	ns	
Fall Time ^c	t _f			30	45		
Drain-Source Body Diode and Charact	eristics (T _C = 2	5 °C) ^b		<u> </u>			
Continuous Current	I _S				- 30		
Pulsed Current	I _{SM}				- 30	A	
Forward Voltage ^a	V _{SD}	I _F = - 19 A, V _{GS} = 0 V		- 1	- 1.5	V	
Reverse Recovery Time	t _{rr}	I _F = - 19 A, di/dt = 100 A/μs		41	61	ns	

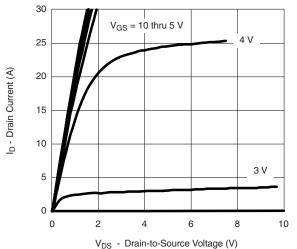
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

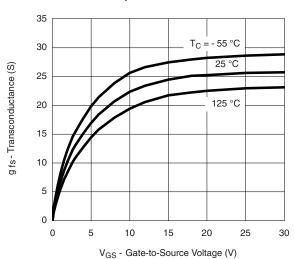
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



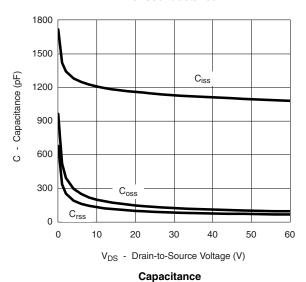
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



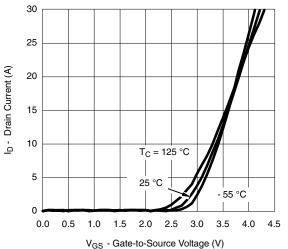
Output Characteristics



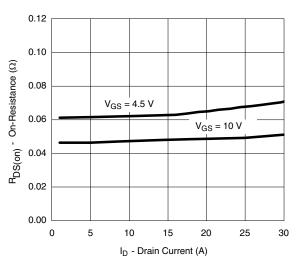
Transconductance



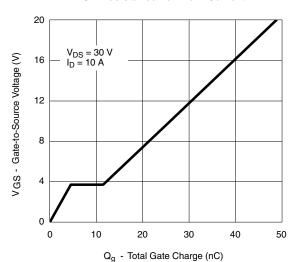
TIFICAL CHARACTERISTICS (25 O, unless otherwise noted)



Transfer Characteristics



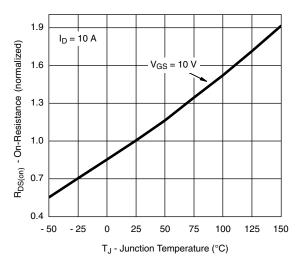
On-Resistance vs. Drain Current



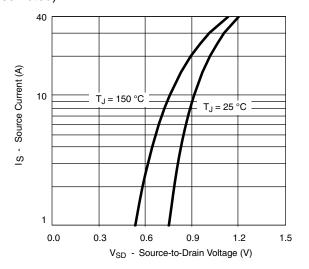
Gate Charge



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage

THERMAL RATINGS

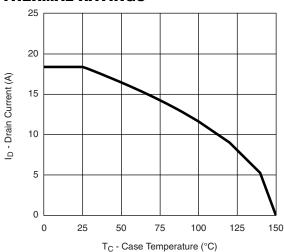
2

0.1

0.01

10-4

Normalized Effective Transient Thermal Impedance



Maximum Drain Current vs. Case Temperature

Duty Cycle = 0.5

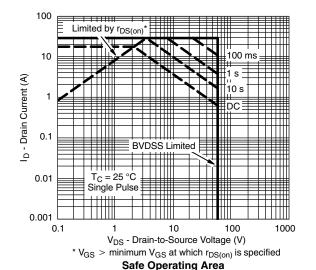
Single Pulse

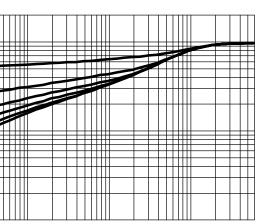
10-3

0.2

0.05

0.02





100

600

10

Square Wave Pulse Duration (sec)

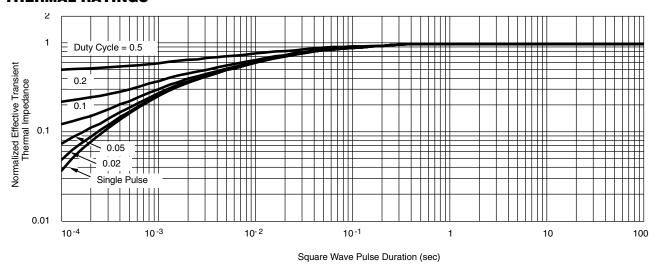
Normalized Thermal Transient Impedance, Junction-to-Ambient

10⁻¹

10-2



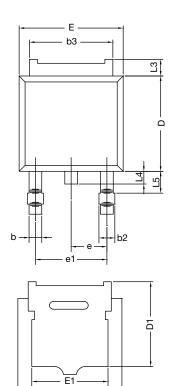
THERMAL RATINGS

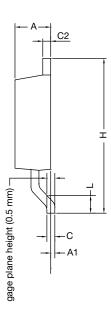


Normalized Thermal Transient Impedance, Junction-to-Case



TO-252AA Case Outline





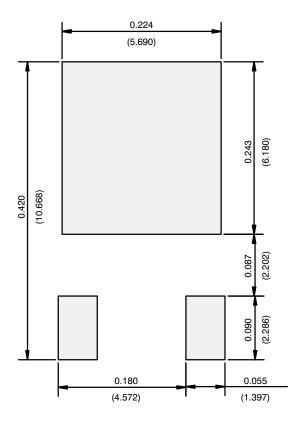
	MILLIMETERS		MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.		
Α	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	4.10	-	0.161	-		
E	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28	2.28 BSC 0.090 BSC		BSC		
e1	4.56	BSC 0.180 E		BSC		
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.01	1.52	0.040	0.060		
ECN: T16-0236-Rev. P, 16-May-16 DWG: 5347						

Notes

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



8

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